[WeB1] HARC Etch and Plasma Source	
Session Date	November 12 (Wed.), 2025
Session Time	09:00-10:25
Session Room	Room B (Grand Ballroom 1, 2F)
Session Chair	Dr. Jie Li (imec, Belgium)

[WeB1-1] [Invited] **09:00-09:30**

Next Generation HARC Etch Technologies Requiring Ultra-High Aspect Ratio, High Selectivity, and Very High Etch Rate for VNAND Device

Kyujin Jang, Hoki Lee, and Jaeho Min (Samsung Electronics Co., Ltd., Korea)

[WeB1-2] [Invited] **09:30-09:55**

3D NAND Dielectric Etch Technology Challenges and Breakthroughs

Dongsoo Lee (Lam Research Korea, Korea)

[WeB1-3] **09:55-10:10**

Investigation of Toroidal Slot Antennas for Microwave Heating and Plasma Generation

Sung-Hyeon Jung and Ho-Jun Lee (Pusan Nat'l Univ., Korea)

[WeB1-4] **10:10-10:25**

Investigation of Plasma Density Distribution and Electron Heating Mechanisms in Capacitively Coupled Plasma

Seong Eun Oh and Ho-Jun Lee (Pusan Nat'l Univ., Korea)